

# EVM User's Guide: MCF8329HS

## MCF8329HS Evaluation Module



### Description

The MCF8329HSEVM allows users to evaluate the performance of a MCF8329HS motor driver. The EVM includes an onboard FTDI chip to convert USB communication, from the micro-USB connector, into UART. An onboard MSP430FR2355 microcontroller (MCU) translates the UART communication into either control signals or I2C formatted data, which is sent to the MCF8329HS device. There are many user-selectable jumpers, resistors, connectors, and test points to assist with evaluating the many features of the MCF8329HS IC and the configurable device-specific settings.

### Get Started

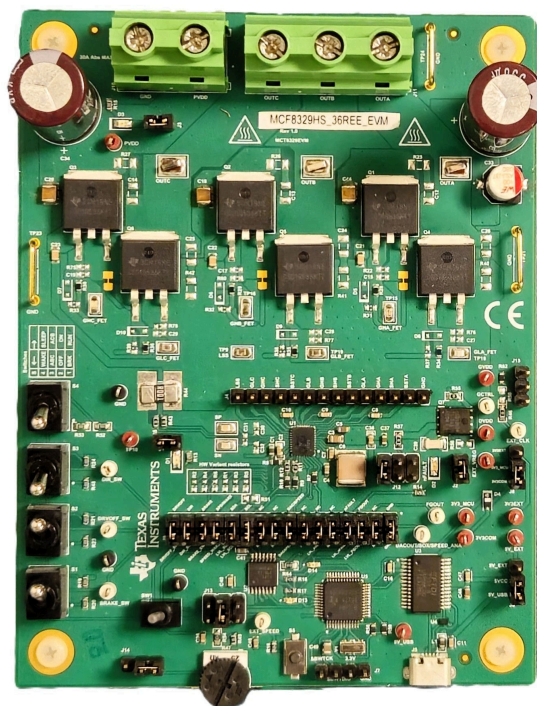
1. Download the latest design files from the [MCF8329HSEVM tool page](#) on ti.com
2. Download the latest version of the Motor Studio GUI and firmware from the [Motor Studio tool page](#) on ti.com

### Features

- GUI software to simplify the MCx tuning process and performance evaluation
- MCU-to-MCx shunt jumper header with removable shunts to disconnect main signals going to the motor driver IC from the MCU
  - The shunts can be removed if the user desires to control the MCF8329HS IC with an external MCU or to use the EVM MCU to control an external MCF8329HS IC

### Applications

- [Cordless vacuum](#)
- [Cordless garden tools](#)
- [CPAP machine](#)
- [Ventilator](#)
- Server fans



MCF8329HSEVM (Top View)

# 1 Evaluation Module Overview

## 1.1 Introduction

This document is provided with the MCF8329HS customer evaluation module (EVM) as a supplement to the MCF8329HS data sheet. This user's guide details the hardware setup instructions, GUI installation, and usage instructions.

### CAUTION

Hot surface temperature

The EVM can have high surface temperatures marked by the FIRE triangular symbol on the EVM. Avoid touching the marked hot surface area when driving high currents to prevent potential burn damage.

## 1.2 Kit Contents

Table 1-1 lists the contents of the EVM kit. Contact the Texas Instruments Product Information Center nearest to you if any components are missing. TI highly recommends that users check the TI website at <https://www.ti.com> to verify that the latest version of the related software is being used.

**Table 1-1. Kit Contents**

Item	Quantity
MCF8329HSEVM	1
USB A Male-to-USB B Micro Male Cable	1

## 1.3 Specification

The MCF8329HSEVM can support voltages up to 60 V and currents up to 30 A. To prevent damage to both the IC and the EVM, confirm that these voltage and current specifications are not exceeded.

## 1.4 Device Information

The MCF8329HS is a 4.5-V to 60-V, three-phase brushless-DC gate driver IC with code-free sensorless field oriented control (FOC) for motor drive applications. The device provides three half-bridge gate drivers, each capable of driving high-side and low-side N-channel power MOSFETs. The device generates the correct gate drive voltages using an internal charge pump and enhances the high-side MOSFETs using a bootstrap circuit. A trickle charge pump is included to support 100% duty cycle. The gate drive architecture supports peak gate drive currents up to 1-A source and 2-A sink.

The internal sensorless FOC algorithm is highly configurable through register settings in a non-volatile EEPROM ranging from motor start-up behavior to closed loop operation, which allows for the device to operate stand-alone once the device has been configured. Motor current is sensed using an integrated current sense amplifier supporting a single external shunt resistor. The device can receive a speed command through a PWM input, analog voltage, variable frequency square wave, or I2C command. There are a large number of protection features integrated into the MCF8329HS, intended to protect the device, motor, and system against fault events.

## 2 Hardware

### 2.1 Quick Start Guide

The MCF8329HSEVM requires a power supply source, which has a recommended operating range from a 4.5-V to 60-V. To setup and power the EVM, follow the sequence below:

1. Connect motor phases to A, B, and C on connector J11.
2. Do not turn on the power supply yet. Connect the motor supply to PVDD and GND on connector J10.
3. Select J6 to 5V\_USB and J8 to 3V3COM to power MSP430 from USB power supply.
4. Connect the micro-USB cable into the computer.
5. Turn the potentiometer fully clockwise to set the motor to zero speed upon power up.
6. Flip the switch S1 to the top to configure BRAKE = RUN, switch S2 to the top to configure DRVOFF = ON, switch S3 to the bottom to configure DIR = ABC, and switch S4 to the bottom to configure WAKE.
7. Flip the switch SW1 to left to configure SPEED/WAKE pin to SPEED mode and DACOUT/SOx/SPEED\_ANA pin to DACOUT mode. Note that flipping the switch SW1 to right configures SPEED/WAKE pin to WAKE mode and DACOUT/SOx/SPEED\_ANA pin to SPEED\_ANA mode. When SW1 is flipped to right, switch S4 can be used to put the device in SLEEP or WAKE mode and potentiometer R47 can be used to apply analog voltage to the DACOUT/SOx/SPEED\_ANA pin.
8. Set J12 to leftmost position (closer to C6) to apply AVDD to VREG.
9. Set J13 to middle position to apply the analog voltage from potentiometer R47 to the SPEED/WAKE pin.
10. Turn on the motor power supply.
11. Use the potentiometer R47 to control the speed of the motor and the switches to disable the motor driver, change the direction, or apply a brake to the motor. Optionally, use the GUI (as shown in [Section 3](#)) to monitor the real-time speed of the motor, put the MCF8329HS into a low-power sleep mode, and read status of the LEDs.

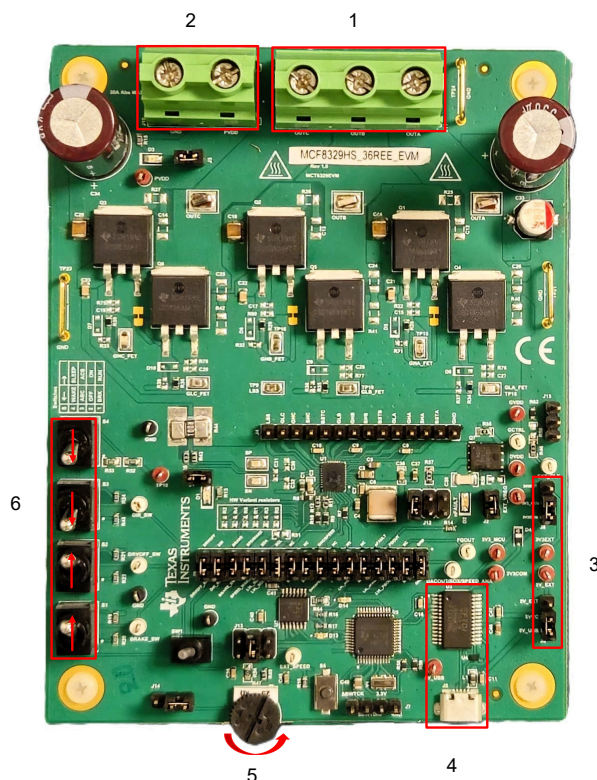


Figure 2-1. Reference for Quick Start Guide

### 2.2 Hardware Setup

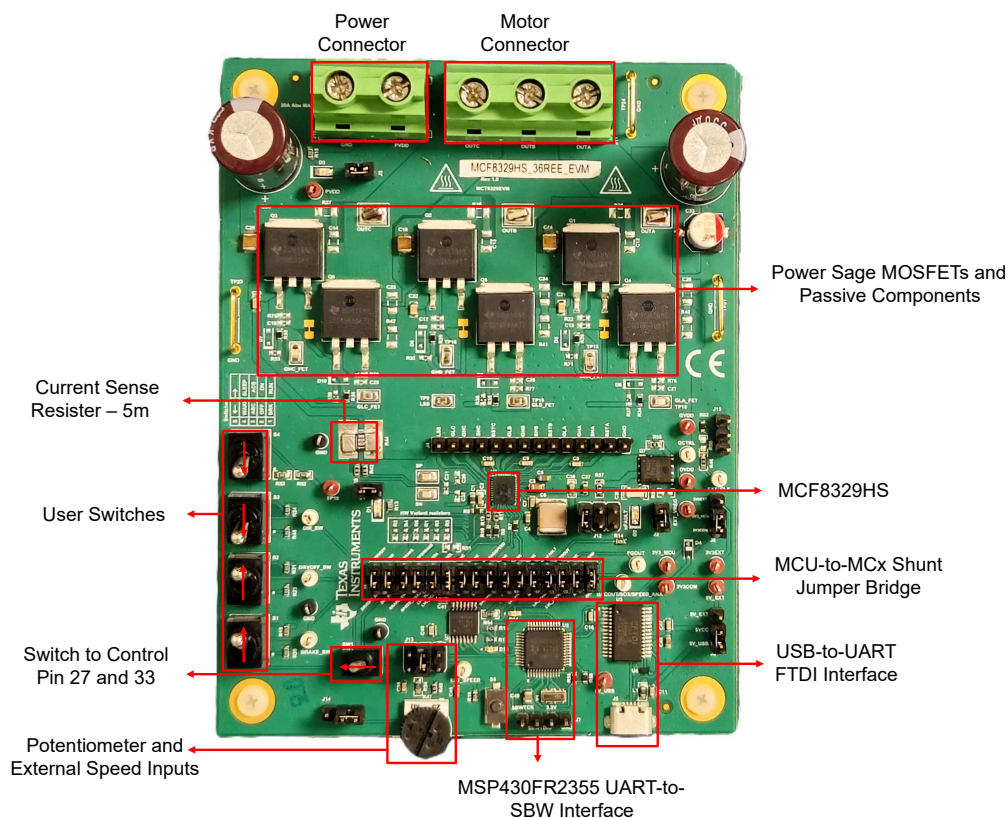
The hardware required to run the motor is the MCF8329HSEVM, a micro-USB cable, and a power supply with a DC output from 4.5-V to 60-V. Follow these steps to start up the MCF8329HSEVM:

1. Connect the DC power supply to header J10. Connect to PVDD and GND.
2. Apply user configurable jumper settings. See [Section 2.7](#) for more information.
3. Turn on the power supply to power up the MCF8329HSEVM.
4. Connect a Micro-USB cable to the MCF8329HSEVM and computer.

If using the MCF8329HSEVM with an external microcontroller, then remove all shunt jumpers from jumper bridge J9. Connect with external jumpers to the right side of the jumper bridge from the external MCU.

## 2.3 Hardware Connections Overview

**Figure 2-2** shows the major blocks of MCF8329HSEVM. The MCF8329HSEVM is designed for an input supply from 4.5 V to 60 V at 30 A max. The MCF8329HSEVM includes a power stage with six external N-channel power MOSFETs (part number: CSD18536KTTT) and passive components. The MCF8329HSEVM also includes a 5 mΩ current sense shunt resistor and an external N-channel MOSFET controlled by GCTRL to generate VREG. For interfacing with the GUI, the MCF8329HSEVM has an onboard FTDI chip and MSP430.



**Figure 2-2. MCF8329HSEVM Major Hardware Blocks**

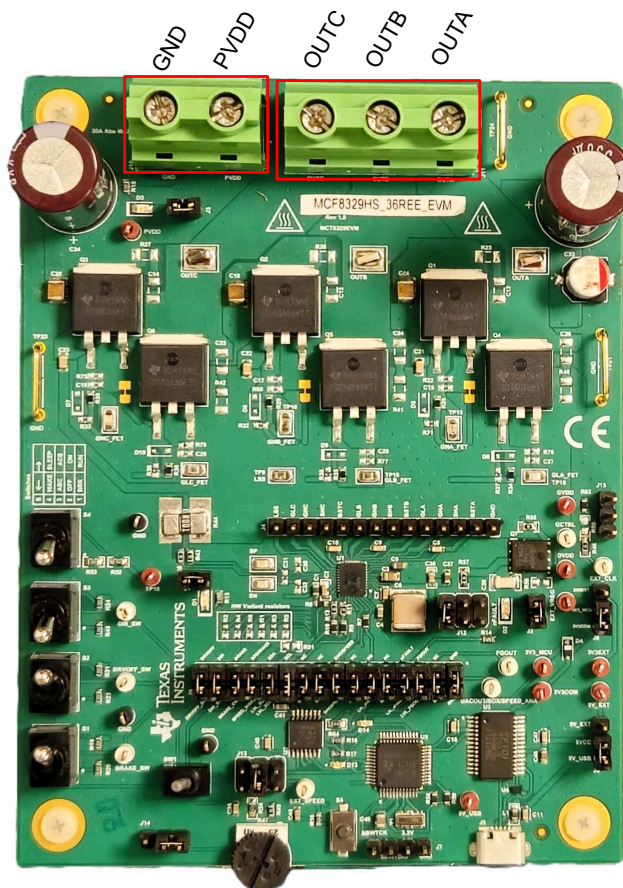


## 2.4 Connection Details

Figure 2-3 outlines which connections must be made to the MCF8329HSEVM to spin a 3-phase sensorless brushless-DC motor.

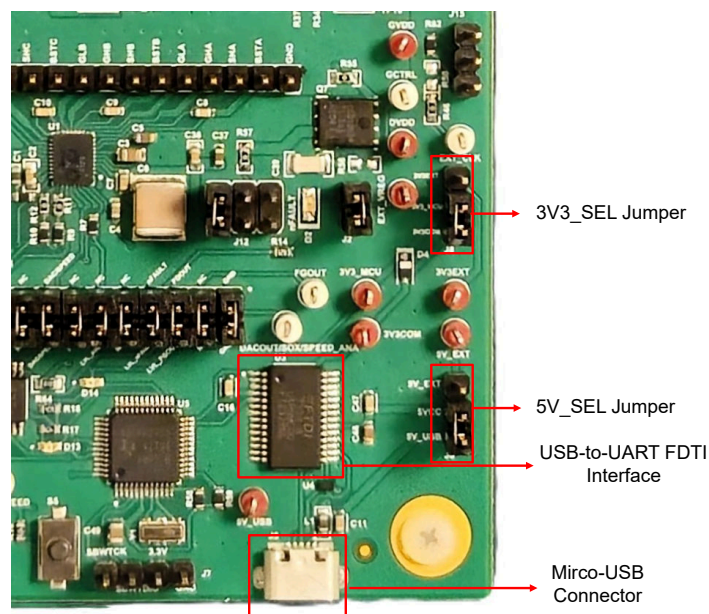
Connect a 4.5-V to 60-V power supply to the PVDD and GND terminals on connector J10.

Connect the three phases of the BLDC motor to the A, B, and C terminals of the screw terminal connector J11.



**Figure 2-3. Connections from Motor to MCF8329HSEVM**

Figure 2-4 shows where the micro-USB cable is plugged into the MCF8329HSEVM to provide communication between evaluation module and GUI. The USB data and 5 V power from the USB is converted, by the FTDI chip, into UART data and 3.3 V power which is used to power the MSP430FR2355 microcontroller. The 5 V from the USB power is limited to 500 mA and the 3.3 V from the FTDI chip is limited to 30 mA. If the user wants to supply more current to these rails, then use the 5V\_SEL jumper J6 and 3V3\_SEL jumper J8 to connect external power rails.



**Figure 2-4. Micro-USB connector and USB-to-UART interface**

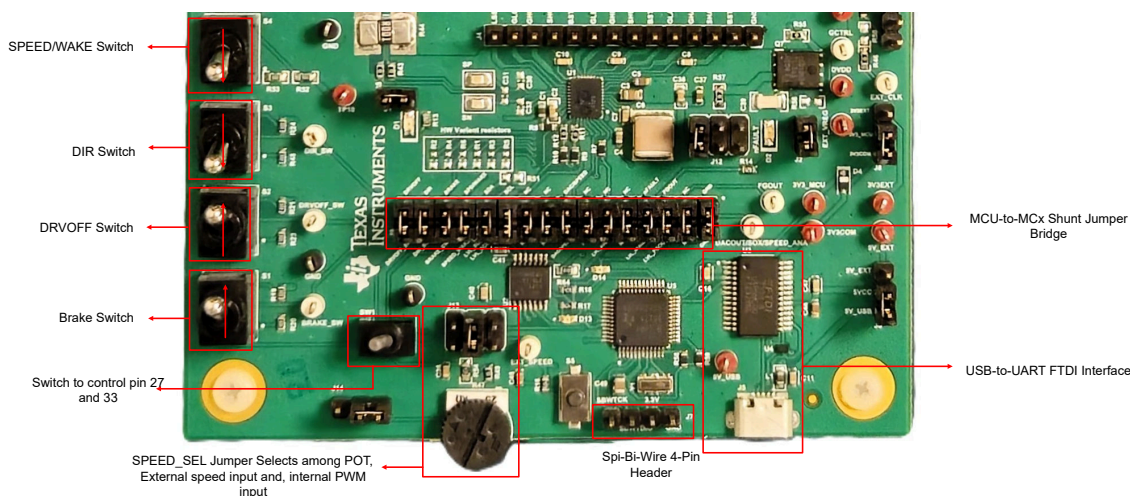
## 2.5 MSP430FR2355 Microcontroller

The MCF8329HSEVM includes a MSP430FR2355 low-power MCU, shown in [Figure 2-5](#), to communicate via I2C with the MCF8329HS IC.

To program the MSP430FR2355, an external MSP430 FET programmer must be connected to the Spy-Bi-Wire (SBW) interface connector J7. Many MSP430 LaunchPads™ provide an onboard eZ-FET Debug Probe that can be jumper-wired to the MCF8329HSEVM to flash the firmware into the onboard MSP430FR2355 microcontroller.

The user can use the Reset (RST) button at any time to restart the MCU program. Two active-low LEDs, D13 and D14, can be used for debug purposes as well.

The 32-pin shunt jumper bridge J9 ties all signals between the microcontroller and MCF8329HS IC. These jumpers can be inserted or removed as needed to isolate the microcontroller from the gate driver. This allows for microcontroller signal debugging or using the MCF8329HSEVM as a standalone gate driver with an external microcontroller.



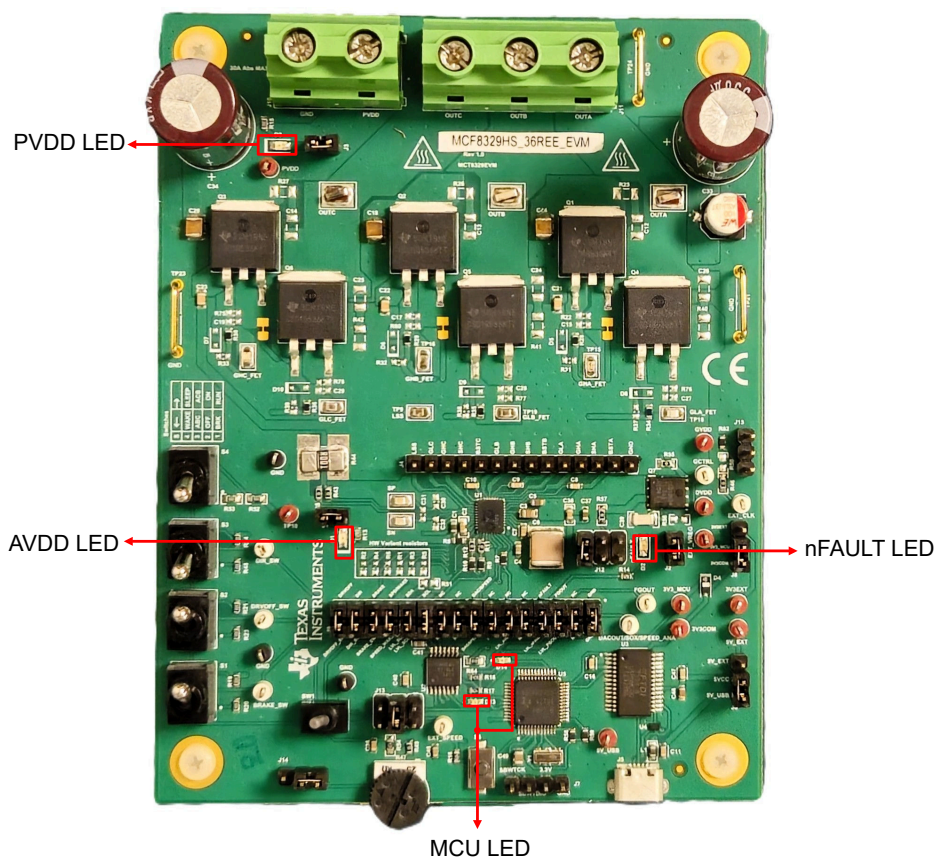
**Figure 2-5. MSP430FR2355 MCU on MCF8329EVM**

## 2.6 LED Lights

The MCF8329HSEVM has 5 status LEDs that provide the status of power supplies and functions of the evaluation module. By default, the PVDD LED and AVDD LED lights up when the board is powered and the program has been flashed onto the microcontroller. [Table 2-1](#) shows LED descriptions including those that are on during power up in bold with [Figure 2-6](#) showing the locations of the LEDs.

**Table 2-1. Description of MCF8329HSEVM LEDs (Default in Bold After Power Up)**

Designator	Name	Color	Description
D1	3.3V	Green	Lights up when AVDD is turned ON
D2	nFAULT	Red	Lights up when fault condition has occurred on MCF8329HS
D3	PVDD	Green	Lights up when voltage is applied on PVDD
D13	MSP_LED1	Red	Used for UART or debugging
D14	MSP_LED2	Red	Used for UART or debugging



**Figure 2-6. MCF8329HSEVM LED Locations**



## 2.7 User Configurable Settings

The MCF8329HSEVM includes a variety of user-selectable jumpers, switches, and resistors on the entirety of the evaluation board to configure settings. [Table 2-2](#) summarizes all of these configurable settings.

**Table 2-2. Description of User-Selectable Settings on MCF8329HSEVM (Default in Bold)**

Designator	Setting Name	Description	Layer	Position	Function
J8	3V3_SEL	Select 3.3 V source for MCU power	Top	J8 = 3V3EXT	External
				J8 = 3V3COM	From FTDI (30 mA)
J6	5V_SEL	Select 5 V source for FTDI power	Top	J6 = 5V_EXT	External
				J6 = 5V_USB	From USB power (500 mA)
J15	Hall sensor	Hall sensor connector	Top	J15 = GND	GND
				J15 = AVDD	AVDD
				J15 = HALL INPUT	Hall sensor input
J14	POT Supply	Supply to POT selection	Top	Left	AVDD
				Right	3V3_MCU
J13	SPEED_SEL	Selects SPEED input source	Top	J13 = EXT	External EXT_SPEED test point
				J13 = POT	From Potentiometer R47
				J13 = INT_PWM	From internal PWM. PWM Duty cycle can be varied by rotating the POT R47
J9	MSP to MCx Shunt jumper bridge	Connects signals from MVU and user switches to MCF8329HS when jumpers are inserted	Top	DRVOFF_SW	DRVOFF
				DIR_SW	DIR
				BRAKE_SW	BRAKE
				SPEED_WAK	SPEED/WAKE
				MSP_POCI/SCL	SCL
				MSP_PICO/SDA	SDA
				NC	NC
				NC	NC
				DAC/SPEED	DAC/SPEED
				NC	NC
				LVL_AVDD	AVDD
				NC	NC
				LVL_nFAULT	nFAULT
				LVL_FGOUT	FGOUT
				NC	NC
				GND	GND
J12	VREG_SEL	Selects VREG power supply	Top	Left position	VREG powered by AVDD
				Middle position	VREG powered externally
				Right position	VREG powered by MOSFET Q7
J1	AVDD LED	Connects AVDD LED to 3.3 V pull up	Top	Connected	D1 lights up when AVDD is turned ON
J2	nFAULT LED	Connects nFAULT LED to 3.3 V pull up	Top	Connected	D2 Lights up when nFAULT is pulled low
J3	PVDD LED	Connects PVDD LED to 3.3 V pull up	Top	Connected	D3 lights up when voltage is applied to PVDD
S1	Brake	Turns on all low-side MOSFETs	Top	Bottom	Break enabled
				Top	Brake disabled



**Table 2-2. Description of User-Selectable Settings on MCF8329HSEVM (Default in Bold) (continued)**

Designator	Setting Name	Description	Layer	Position	Function
S2	DRVOFF	Disables gate drivers	Top	Bottom	MCF8329HS Disabled
				<b>Top</b>	MCF8329HS Disabled
S3	DIR	Controls direction of motor rotation	Top	Bottom	ABC
				Top	ACB
S4	SPEED/WAKE	Pulls SPEED/WAKE pin to AVDD and GND	Top	Bottom	SPEED/WAKE pin pulled to AVDD
				Top	SPEED/WAKE pin pulled to GND
SW1	N/A	Configure SPEED/WAKE pin to SPEED mode and DACOUT/SOx/ SPEED_ANA pin	Top	Left	Configure SPEED/Wake pin to SPEED mode and DCAOUT/SOx/ SPEED_ANA pin to DACOUT mode
				Right	Configure SPEED/WAKE pin to WAKE mode and DACOUT/SOx/ SPEED_ANA pin to SPEED_ANA mode

## 3 Software

### 3.1 Firmware and GUI Application

The MCF8329HSEVM includes a USB-to-UART interface, using a MSP430FR2355 microcontroller, that serves as a communication bridge between a host PC and the MCF8329HS device for configuring various device settings and reading fault diagnostic information.

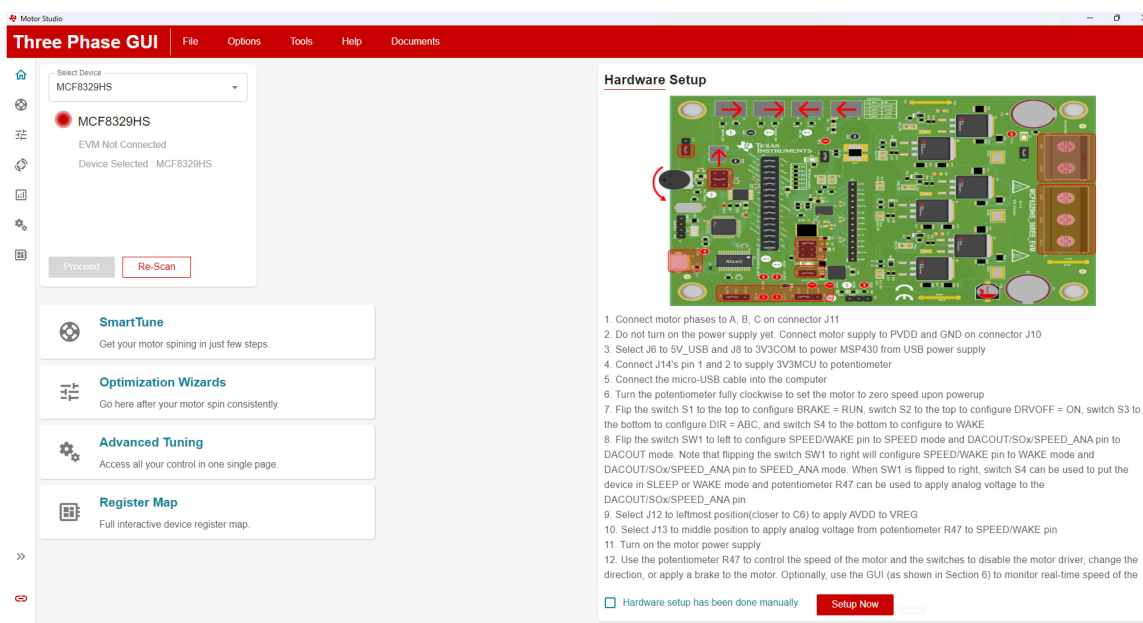
The MCF8329HSEVM is supported on the Motor Studio GUI which can be used to configure the MCF8329HS through this communication interface. The Motor Studio GUI simplifies the tuning process of the MCF8329HS by offering guided tuning instructions, a virtual oscilloscope for real-time variable monitoring, and more. The latest version of the [Motor Studio GUI](#) can be downloaded on ti.com.

By default, the onboard MSP430 microcontroller already contains the firmware needed to communicate with the Motor Studio GUI. If there is a firmware update or the GUI does not connect to the EVM, then the user must flash the firmware code into the MSP430 by following the steps outlined in [Section 3.4](#).

Flashing the firmware code onto the MSP430 requires an integrated development environment (IDE) and an eZ-FET Debug Probe. The following example uses the [Code Composer Studio™ \(CCS\)](#) IDE and the [MSP-EXP430FR2355 LaunchPad™ Development Kit](#) to provide the eZ-FET Debug Probe.

### 3.2 Downloading and Running Motor Studio

1. Connect the MCF8329HSEVM as described in [Section 2.2](#).
2. Download the latest version of the [Motor Studio GUI](#).
3. Once the Motor Studio GUI is installed, run the Motor Studio GUI application.
4. Click the red *Setup Now* button under *Hardware Setup* on the bottom right side of the window.
5. After setting up the hardware settings of the MCF8329HSEVM, click on the *SmartTune* option to begin configuring the device.



**Figure 3-1. Motor Studio GUI MCF8329HS Home Page**

### 3.3 Downloading Code Composer Studio and Importing GUI Firmware

1. Download and extract the [Motor Studio firmware](#) to a location on your computer.
2. Download the latest version of [Code Composer Studio](#) to set up a folder in the directory C:\ti.
  - a. Accept all agreements, default install instructions, and select *Next* to proceed through the menus.
  - b. In the *Selected Components* window, make sure to check *MSP430 Low-Power MCUs* to install the required packages for the MSP430 Launchpad Evaluation Kits.
3. After installing, run CCS and select a folder or the default to use as the workspace to store any new projects. The location and naming convention can be changed based on the user's preference. Click the OK button to accept.
4. In CCS, click on the Project tab and select *Import CCS Projects*. Click on *Browse*.
5. Select the folder created in step 1 by extracting the Motor Studio firmware.
6. Import the project into your workspace as shown in [Figure 3-2](#)

```

1/* --COPYRIGHT--,BSD
2 * Copyright (c) 2018, Texas Instruments Incorporated
3 * All rights reserved.
4 *
5 * Redistribution and use in source and binary forms, with or without
6 * modification, are permitted provided that the following conditions
7 * are met:
8 *
9 * Redistributions of source code must retain the above copyright
10 * notice, this list of conditions and the following disclaimer.
11 *
12 * Redistributions in binary form must reproduce the above copyright
13 * notice, this list of conditions and the following disclaimer in the
14 * documentation and/or other materials provided with the distribution.
15 *
16 * Neither the name of Texas Instruments Incorporated nor the names of
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18 * from this software without specific prior written permission.
19 *
20 * THIS SOFTWARE IS PROVIDED BY THE COPYRIGHT HOLDERS AND CONTRIBUTORS "AS IS"
21 * AND ANY EXPRESS OR IMPLIED WARRANTIES, INCLUDING, BUT NOT LIMITED TO,
22 * THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR
23 * PURPOSE ARE DISCLAIMED. IN NO EVENT SHALL THE COPYRIGHT OWNER OR
24 * CONTRIBUTORS BE LIABLE FOR ANY DIRECT, INDIRECT, INCIDENTAL, SPECIAL,
25 * EXEMPLARY, OR CONSEQUENTIAL DAMAGES (INCLUDING, BUT NOT LIMITED TO,
26 * PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES; LOSS OF USE, DATA, OR PROFITS;
27 * OR BUSINESS INTERRUPTION) HOWEVER CAUSED AND ON ANY THEORY OF LIABILITY,
28 * WHETHER IN CONTRACT, STRICT LIABILITY, OR TORT (INCLUDING NEGLIGENCE OR
29 * OTHERWISE) ARISING IN ANY WAY OUT OF THE USE OF THIS SOFTWARE,
30 * EVEN IF ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.
31 * --COPYRIGHT--*/
32/*****
33//
34// MSP430FR2355 firmware for compatibility with Motor Studio
35//
36// E. Chen
37// Texas Instruments Inc.
38// May 2018
39/*****
40
41#include <driverlib.h>
42#include <stdint.h>
43#include <stdbool.h>
44#include <stdio.h>
45#include <stdlib.h>
46#include <string.h>
47#include <jsmn.h>
48
49/* Constants */
50#define MAX_STR_LEN 256
51#define INTER_BYTE_DELAY 2800 // at least 100 us
52#define I2C_TIMEOUT 65535
  
```

**Figure 3-2. MSP430FR2355 Interface Firmware Code in Code Composer Studio**

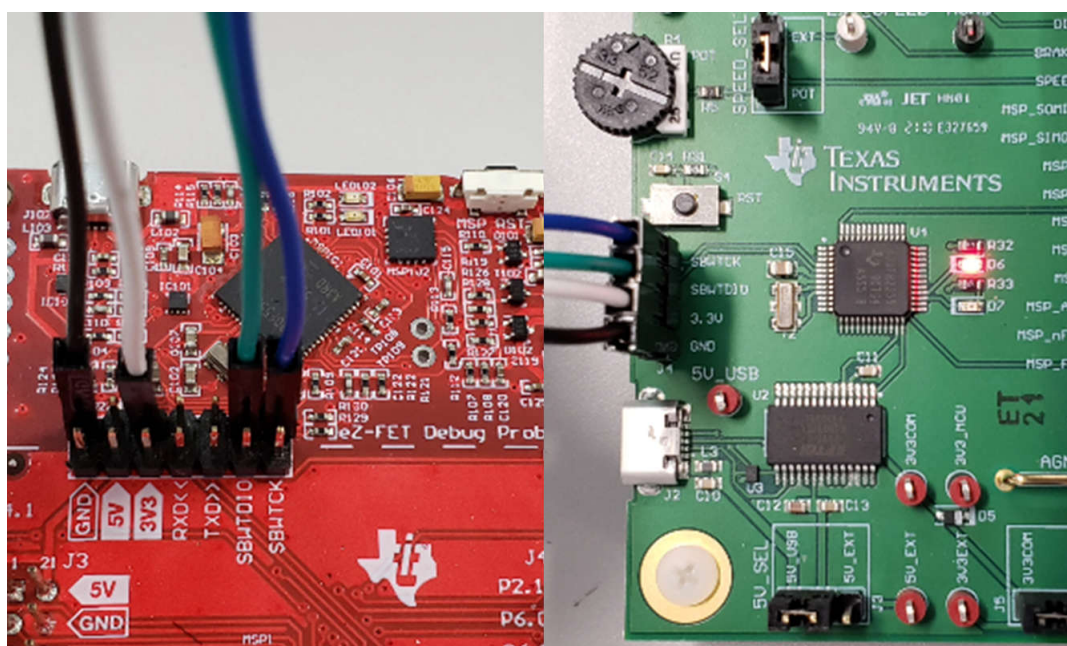
### 3.4 Using eZ-FET to Program the Onboard MSP430FR2355

The eZ-FET Debug Probe on the MSP430FR2355 LaunchPad uses a Spy-Bi-Wire JTAG interface to program the MSP430FR2355 MCU on the MCF8329HSEVM. Consult the [MSP430 Launchpad Development Kits](#) for MSP430 Launchpad the include an onboard eZ-FET Debug Probe.

1. Remove the GND, 3V3, SBWTDIO, and SBWTCK jumpers from the MSP430 LaunchPad.
2. Connect the top pins on the eZ-FET side of the LaunchPad of the GND, 3V3, SBWTDIO, SBWTCK signals to the respective pins on J7 of the MCF8329HSEVM as shown in [Table 3-1](#) and [Figure 3-3](#).
3. Connect a micro-USB cable to the MSP430 LaunchPad and the PC.
4. Click on the Build Project icon or CTRL+B to make sure the project builds successfully. Accept any updates if needed from the console
5. Click on Debug Project to set up a debug session and press the Play button to run the code.
6. Stop the debug session, close Code Composer Studio, disconnect the Spy-Bi-Wire jumpers, and unplug the micro-USB cable from the MSP430 LaunchPad.

**Table 3-1. Spy-Bi-Wire Connections Needed to Program the MSP430FR2355**

MSP430 LaunchPad (eZ-FET Debug Probe Side) (J101)	MCF8329HSEVM 4-pin Spy-Bi-Wire Header (J7)
GND	GND
3V3	3V3
SBWTDIO	SBWTDIO
SBWTCK	SBWTCK



**Figure 3-3. MSP430 LaunchPad eZ-FET Debug Probe Connected to MSP430FR2355**





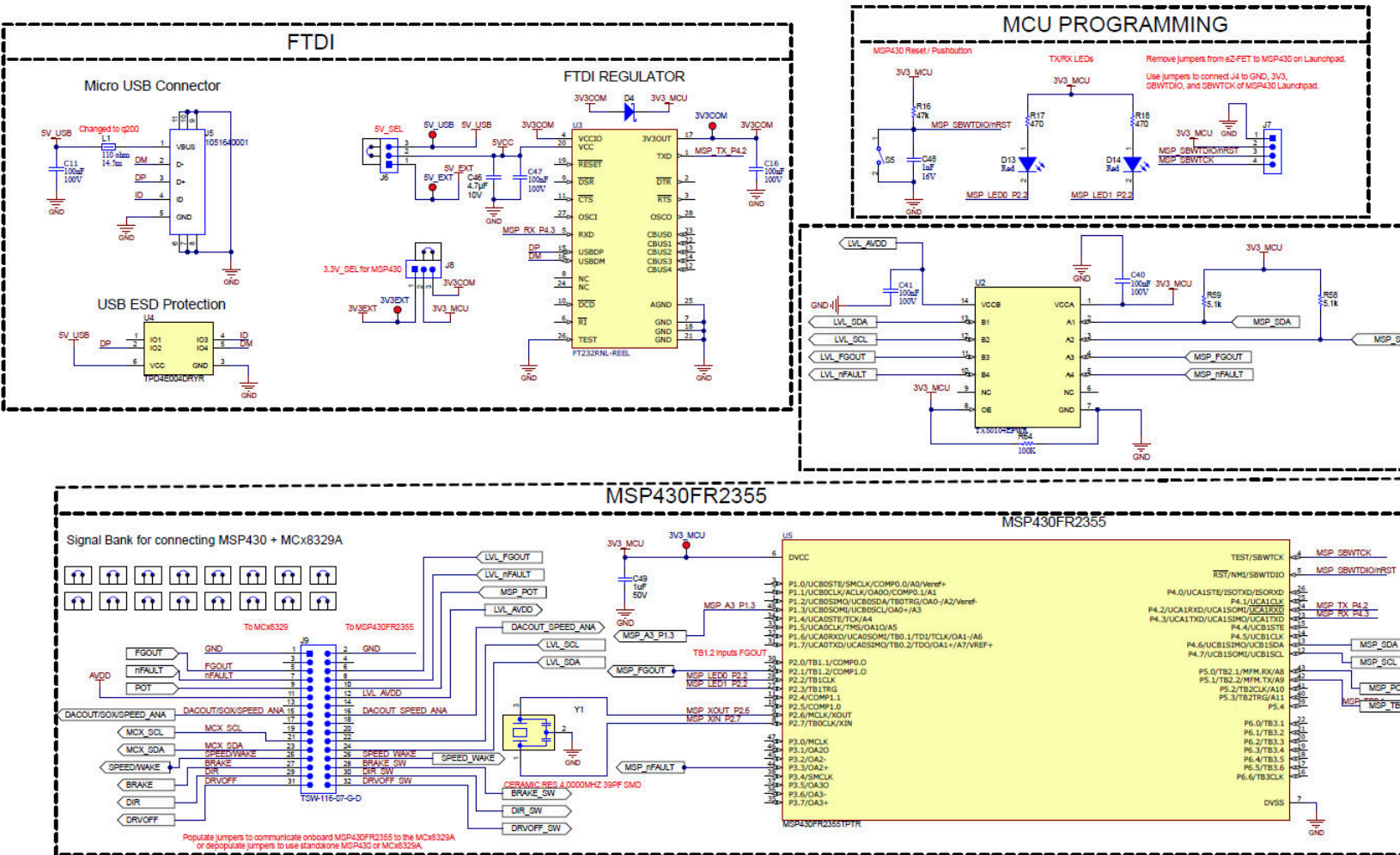


Figure 4-2. Driver

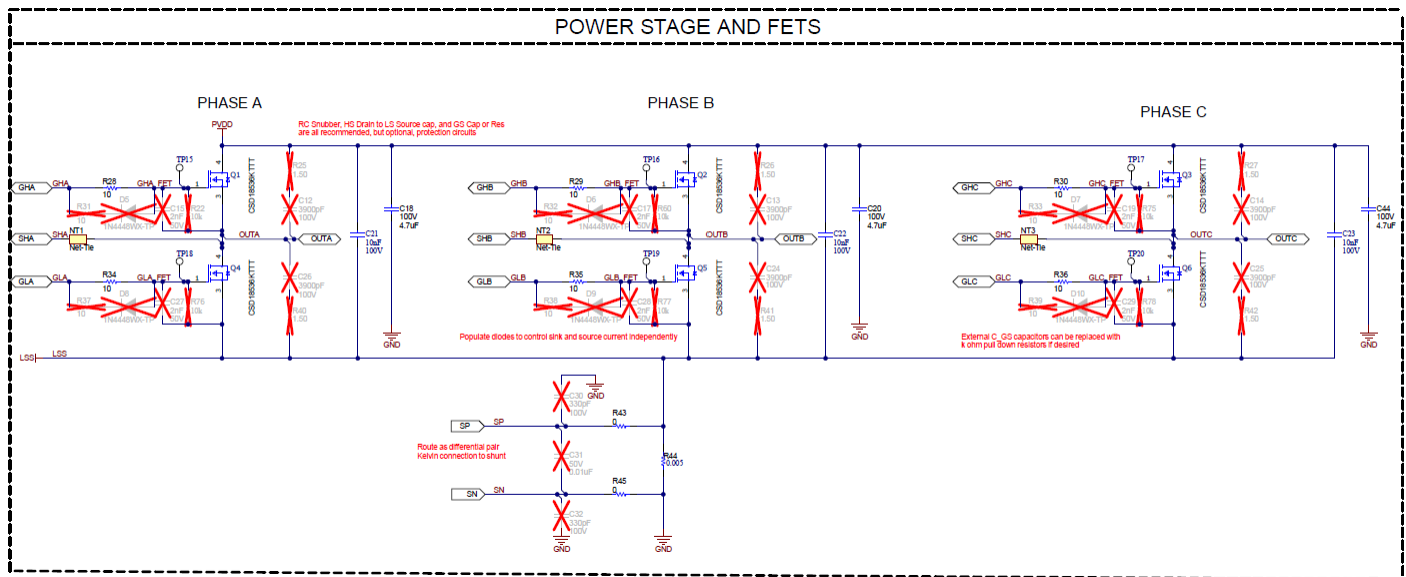
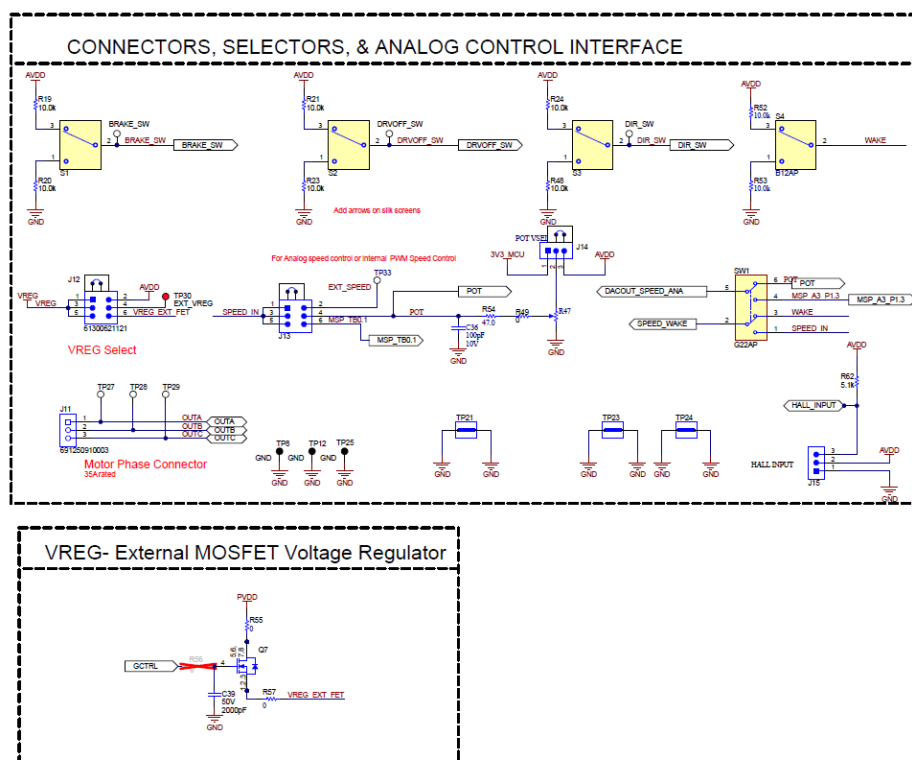
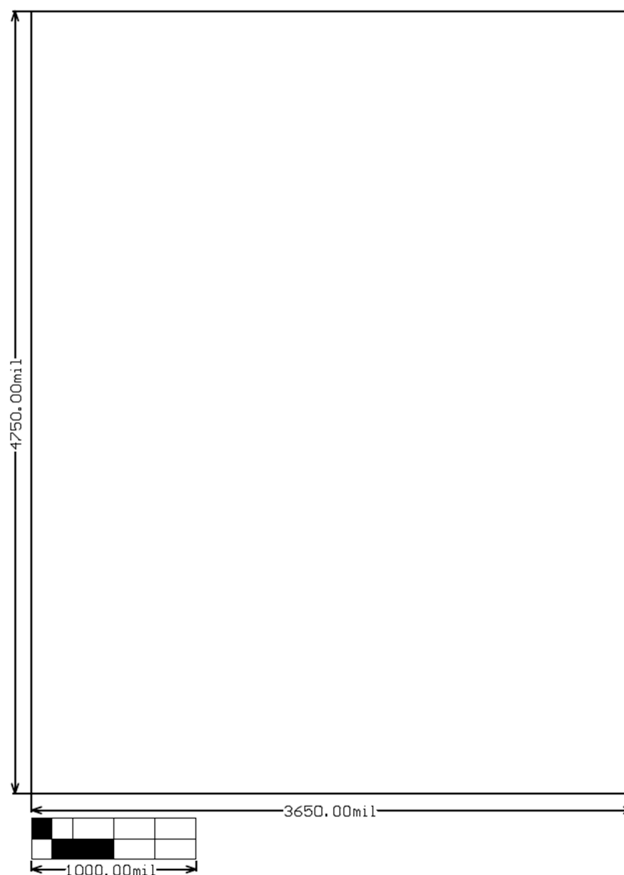


Figure 4-3. MOSFETs and Power Stage



### Figure 4-4. Power and Connectors

## 4.2 PCB Layouts



**Figure 4-5. EVM Board Dimensions**



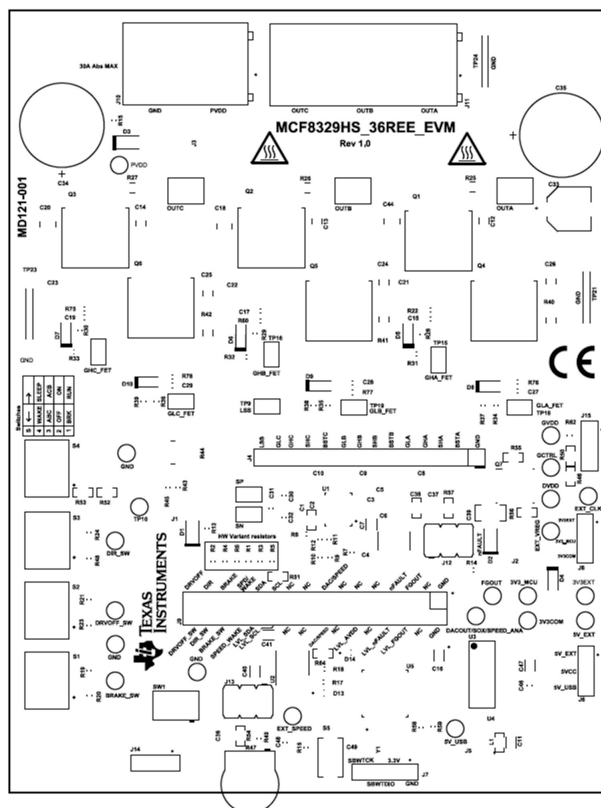


Figure 4-6. EVM Top Overlay

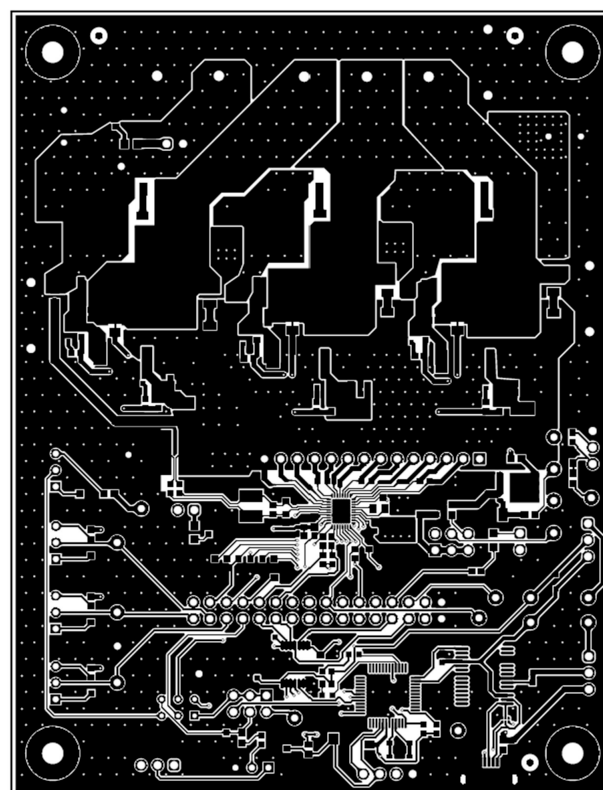


Figure 4-7. EVM Top Layer

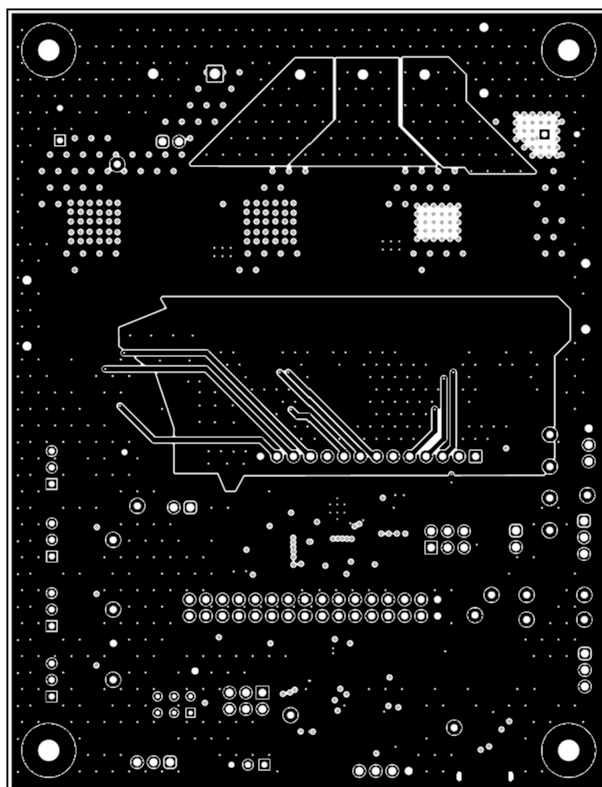


Figure 4-8. EVM Signal Layer 1

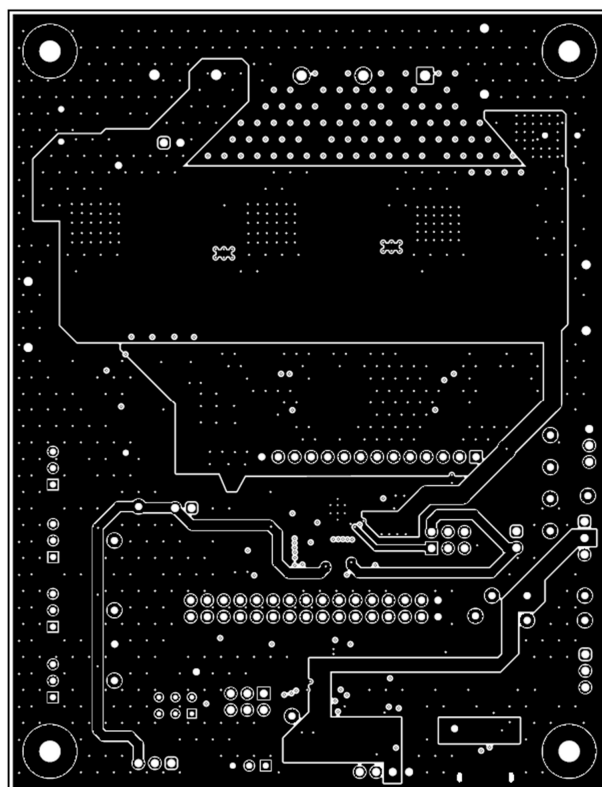
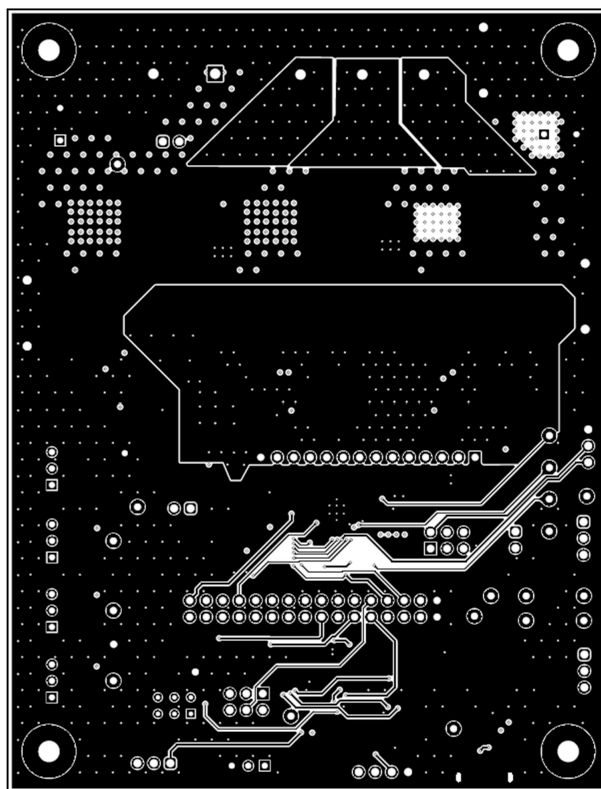


Figure 4-9. EVM Signal Layer 2



**Figure 4-10. EVM Bottom Layer**

### 4.3 Bill of Materials (BOM)

**Table 4-1. Bill of Materials (BOM)**

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
C1, C37	2	10uF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0603, X5R, 10μF, 6.3VDC	603	885012106006	Würth Elektronik
C12, C13, C14, C24, C25, C26	0	3900pF	CAP CER 3900PF 100V X7R 1206	1206	12061C392KAZ2A	AVX Corporation
C18, C20, C44	3	4.7uF	CAP, CERM, 4.7 uF, 100 V, +/- 10%, X7S, 1210	1210	GRM32DC72A475KE01 L	MuRata
C2, C38	2	0.1uF	CAP, CERM, 0.1 uF, 10 V, +/- 10%, X7R, 0603	603	885012206020	Würth Elektronik
C21, C22, C23	3	10nF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0805, X7R, 10nF, 100VDC	805	885012207122	Würth Elektronik
C3	1	470nF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0805, X7R Class II, 470nF, 100VDC	805	885012207130	Würth Elektronik
C30, C32	0	330pF	CAP, CERM, 330 pF, 100 V, +/- 10%, X7R, 0603	603	06031C331KAT2A	AVX
C31	0	0.01uF	CAP, CERM, 0.01 uF, 50 V, +/- 5%, C0G/NP0, 0603	603	C1608NP01H103J080A A	TDK
C33	1	10uF	WCAP-ASLI Aluminum Electrolytic Capacitor, V-Chip, D6.3 x H7.7mm, 10uF, 80V	D6.3 x H7.7mm	865081745005	Würth Elektronik
C34, C35	2	390uF	CAP, AL, 390 uF, 100 V, +/- 20%, 0.026 ohm, TH	D12.5xL35 mm	EKYB101ELL391MK35S	Chemi-Con
C36	1	100pF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0603, X7R, 100pF, 10VDC	603	885012206003	Würth Elektronik
C39	1	2000pF	CAP, CERM, 2000 pF, 50 V, +/- 5%, C0G/NP0, 1206	1206	12065A202JAT2A	AVX
C4	1	1uF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0603, X5R, 1μF, 6.3VDC	603	885012106003	Würth Elektronik
C46	1	4.7uF	CAP, CERM, 4.7 uF, 10 V, +/- 20%, X7R, 0603	603	GRM188Z71A475ME15 D	MuRata
C48	1	1000pF	CAP, CERM, 1000 pF, 16 V, +/- 10%, X7R, 0603	603	885012206034	Würth Elektronik
C49	1	1uF	CAP, CERM, 1 uF, 50 V, +/- 10%, X7R, 0805	805	885012207103	Würth Elektronik
C5	1	10uF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0603, X5R, 10μF, 25VDC	603	885012106031	Würth Elektronik
C6	1	10uF	CAP, CERM, 10 uF, 100 V, +/- 20%, X7R, 2220	2220	22201C106MAT2A	AVX
C7, C11, C16, C40, C41, C47	6	100nF	0.1 μF ±10% 100V Ceramic Capacitor X7R 0603 (1608 Metric)	603	885012206120	Würth Electronics
C8, C9, C10	3	1uF	WCAP-CSGP Multilayer Ceramic Chip Capacitor, General Purpose, size 0603, X5R, 1μF, 25VDC	603	885012106022	Würth Elektronik
D1, D3	2	Bright Green	LED, Bright Green, SMD	LED_0805	150080VS75000	Würth Elektronik
D13, D14	2	Red	Red 625nm LED Indication - Discrete 2V 0603 (1608 Metric)	603	150060RS75003	Würth Electronics



**Table 4-1. Bill of Materials (BOM) (continued)**

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
D2	1	Red	LED, Red, SMD	LED_0805	150080RS75000	Würth Elektronik
D4	1	40V	Diode, Schottky, 40 V, 0.75 A, AEC-Q101, SOD-323	SOD-323	BAT165E6327HTSA1	Infineon Technologies
D5, D6, D7, D8, D9, D10	0	75V	Diode, Switching, 75 V, 0.25 A, SOD-323	SOD-323	1N4448WX-TP	Micro Commercial Components
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	N/A
H1, H2, H3, H4	4		Standoff, Hex, 1"L #4-40 Nylon	Standoff	1902E	Keystone
H5, H6, H7, H8	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw	NY PMS 440 0025 PH	B&F Fastener Supply
J1, J2, J3	3		Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH	61300211121	Würth Elektronik
J10	1		2 Position Wire to Board Terminal Block Horizontal with Board 0.375" (9.53mm) Through Hole	CONN_TE RM_BLK2	691250910002	Würth Electronics
J11	1		3 Position Wire to Board Terminal Block Horizontal with Board 0.375" (9.53mm) Through Hole	CONN_TE RM_BLK3	691250910003	Würth Electronics
J12, J13	2		Header, 2.54mm, 3x2, Gold, TH	Header, 2.54mm, 3x2, TH	61300621121	Würth Elektronik
J4	1		Header, 100mil, 14x1, Gold, TH	14x1 Header	TSW-114-07-G-S	Samtec
J5	1		Receptacle, USB 2.0, Micro B, 5 Position, R/A, SMT	Receptacle, USB 2.0, Micro B, 5 Pos, 0.65mm Pitch, R/A, SMT	1051640001	Molex
J6, J8, J14, J15	4		Header, 2.54 mm, 3x1, Gold, TH	Header, 2.54mm, 3x1, TH	61300311121	Würth Elektronik
J7	1		Header, 2.54 mm, 4x1, Gold, TH	Header, 2.54mm, 4x1, TH	61300411121	Würth Elektronik
J9	1		Header, 100mil, 16x2, Gold, TH	16x2 Header	TSW-116-07-G-D	Samtec
L1	1	110 ohm	Ferrite Bead, 110 ohm @ 100 MHz, 4.1 A, 0603	603	74279228111	Würth Elektronik
Q1, Q2, Q3, Q4, Q5, Q6	6		MOSFET 60-V, N channel NexFET power MOSFET, single D2PAK, 1.6 mOhm 3-DDPAK/TO-263 -55 to 175	DDPAK	CSD18536KTTT	Texas Instruments
Q7	1	60V	MOSFET, N-CH, 60 V, 50 A, DQJ0008A (VSONP-8)	DQJ0008A	CSD18534Q5A	Texas Instruments
R1, R2, R3, R4, R5, R6, R56	0	0	RES, 0, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	ERJ-3GEY0R00V	Panasonic

**Table 4-1. Bill of Materials (BOM) (continued)**

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
R11, R12, R43, R45, R46, R49, R55, R57	8	0	RES, 0, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	ERJ-3GEY0R00V	Panasonic
R13, R14	2	820	RES, 820, 5%, 0.1 W, 0603	603	RC0603JR-07820RL	Yageo
R15	1	2.00k	RES, 2.00 k, 0.1%, 0.1 W, 0603	603	RG1608P-202-B-T5	Susumu Co Ltd
R16	1	47k	RES, 47 k, 5%, 0.1 W, 0603	603	RC0603JR-0747KL	Yageo
R17, R18	2	470	RES, 470, 5%, 0.1 W, 0603	603	RC0603JR-07470RL	Yageo
R19, R20, R21, R23, R24, R48, R52, R53	8	10.0k	RES, 10.0 k, 0.05%, 0.1 W, AEC-Q200 Grade 0, 0603	603	ERA-3ARW103V	Panasonic
R22, R60, R75, R76, R77, R78	0	10k	RES, 10 k, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	CRCW060310K0JNEA	Vishay-Dale
R25, R26, R27, R40, R41, R42	0	1.5	RES, 1.50, 1%, 0.25 W, AEC-Q200 Grade 0, 1206	1206	CRCW12061R50FKEA	Vishay-Dale
R28, R29, R30, R34, R35, R36	6	10	RES, 10, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	CRCW060310R0JNEA	Vishay-Dale
R31, R32, R33, R37, R38, R39	0	10	RES, 10, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	CRCW060310R0JNEA	Vishay-Dale
R44	1	5m	5 mOhms $\pm$ 1% 7W Chip Resistor Nonstandard Automotive AEC-Q200, Current Sense, Moisture Resistant, Pulse Withstanding Metal Element	2818	WSHM28185L000FEA	Vishay
R47	1	25 kohm	Trimmer Potentiometer, 25kohm, 0.5W, TH	9.53x8.89mm	3352T-1-253LF	Bourns
R50	0	1.00Meg	RES, 1.00 M, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	603	RMCF0603FG1M00	Stackpole Electronics Inc
R51	0	100k	RES, 100 k, 0.1%, 0.1 W, 0603	603	RT0603BRD07100KL	Yageo America
R54	1	47	RES, 47.0, 0.1%, 0.1 W, 0603	603	RT0603BRD0747RL	Yageo America
R64	1	100k	RES, 100 k, 0.1%, 0.1 W, 0603	603	RT0603BRD07100KL	Yageo America
R7, R8, R9, R10, R58, R59, R62	7	5.1k	RES, 5.1 k, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	603	CRCW06035K10JNEA	Vishay-Dale
S1, S2, S3, S4	4		SWITCH TOGGLE SPDT 0.4VA 28V	6.8x23.1x8.8mm	B12AP	NKK Switches
S5	1		Switch, Tactile, SPST, 12 V, SMD	SMD, 6x3.9mm	434121025816	Würth Elektronik

**Table 4-1. Bill of Materials (BOM) (continued)**

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
SH-J1, SH-J2, SH-J3, SH-J4, SH-J5, SH-J6, SH-J7, SH-J8, SH-J10, SH-J11, SH-J12, SH-J13, SH-J14, SH-J15, SH-J16, SH-J17, SH-J18, SH-J19, SH-J20, SH-J21, SH-J22, SH-J23, SH-J24, SH-J25	24	1x2	Shunt, 2.54mm, Gold, Black	Shunt, 2.54mm, Black	60900213421	Würth Elektronik
SW1	1		Switch, DPDT, On-On, 0.4 VA, 28 V, TH	DPDT Switch, 4.5x7mm	G22AP	NKK Switches
TP1, TP10, TP14, TP30, TP40, TP41, TP42, TP43, TP44, TP45	10		Test Point, Miniature, Red, TH	Red Miniature Testpoint	05000	Keystone
TP2, TP3, TP4, TP5, TP26, TP31, TP32, TP33	8		Test Point, Miniature, White, TH	White Miniature Testpoint	05002	Keystone
TP21, TP23, TP24	3		1mm Uninsulated Shorting Plug, 10.16mm spacing, TH	Shorting Plug, 10.16mm spacing, TH	D3082-05	Harwin
TP27, TP28, TP29	3		Test Point, Compact, SMT	Testpoint_Keystone_Compact	05016	Keystone
TP8, TP12, TP25	3		Test Point, Miniature, Black, TH	Black Miniature Testpoint	05001	Keystone
TP9, TP11, TP15, TP16, TP17, TP18, TP19, TP20, TP39	9		Test Point, Miniature, SMT	Testpoint_Keystone_Miniature	05015	Keystone
U1	1		High Speed Sensorless Trapezoidal Control 4.5 to 60 V Three-phase BLDC Gate Driver	WQFN36	MCF8329HSIREER	Texas Instruments
U2	1		4-Bit Bidirectional Voltage-Level Shifter for Open-Drain and Push-Pull Applications, PW0014A (TSSOP-14)	PW0014A	TXS0104EPWR	Texas Instruments
U3	1		UART Interface IC USB Full Speed to Serial UART IC, Includes Oscillator and EEPROM, SSOP-28	SSOP28	FT232RNL-REEL	FTDI
U4	1		4-Channel ESD Protection Array for High-Speed Data Interfaces, DRY0006A (USON-6)	DRY0006A	TPD4E004DRYR	Texas Instruments
U5	1		CPU16 MSP430™ FRAM Microcontroller IC 16-Bit 24MHz 32KB (32K x 8) FRAM 48-LQFP (7x7)	LQFP48	MSP430FR2355TPTR	Texas Instruments

**Table 4-1. Bill of Materials (BOM) (continued)**

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
Y1	1		Resonator, 4 MHz, 39 pF, AEC-Q200 Grade 1, SMD	4.5x1.2x2 mm	CSTCR4M00G55B-R0	MuRata



## 5 Additional Information

### 5.1 Trademarks

LaunchPads™, Code Composer Studio™, and MSP-EXP430FR2355 LaunchPad™ are trademarks of Texas Instruments.

All trademarks are the property of their respective owners.

## STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
  - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
  - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
  - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

### **WARNING**

**Evaluation Kits are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems.**

**User shall operate the Evaluation Kit within TI's recommended guidelines and any applicable legal or environmental requirements as well as reasonable and customary safeguards. Failure to set up and/or operate the Evaluation Kit within TI's recommended guidelines may result in personal injury or death or property damage. Proper set up entails following TI's instructions for electrical ratings of interface circuits such as input, output and electrical loads.**

**NOTE:**

EXPOSURE TO ELECTROSTATIC DISCHARGE (ESD) MAY CAUSE DEGRADATION OR FAILURE OF THE EVALUATION KIT; TI RECOMMENDS STORAGE OF THE EVALUATION KIT IN A PROTECTIVE ESD BAG.

### 3 Regulatory Notices:

#### 3.1 United States

##### 3.1.1 Notice applicable to EVMs not FCC-Approved:

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

##### 3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

#### **CAUTION**

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### **FCC Interference Statement for Class A EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*

#### **FCC Interference Statement for Class B EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:*

- *Reorient or relocate the receiving antenna.*
- *Increase the separation between the equipment and receiver.*
- *Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.*
- *Consult the dealer or an experienced radio/TV technician for help.*

#### 3.2 Canada

##### 3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

#### **Concerning EVMs Including Radio Transmitters:**

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### **Concernant les EVMs avec appareils radio:**

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### **Concerning EVMs Including Detachable Antennas:**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

#### 3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see [http://www.tij.co.jp/sds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/sds/ti_ja/general/eStore/notice_01.page) 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。

<https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-delivered-in-japan.html>

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けていないものがあります。技術適合証明を受けていないもののご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。 日本テキサス・インスツルメンツ株式会社  
東京都新宿区西新宿 6 丁目 2 4 番 1 号  
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3.3.3 *Notice for EVMs for Power Line Communication:* Please see [http://www.tij.co.jp/sds/ti\\_ja/general/eStore/notice\\_02.page](http://www.tij.co.jp/sds/ti_ja/general/eStore/notice_02.page)

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#### 3.4 European Union

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

#### 4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

##### 4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

#### 6. *Disclaimers:*

6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.

6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.

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8. *Limitations on Damages and Liability:*

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